

1/7

Top Cladding Layer 11				
	Core 10a		Core 10b	
Bottom Cladding Layer 12				
Si Substrate 13				

FIG. 1 (Prior Art)



2/7

Thermo-optic Mach Zehnder

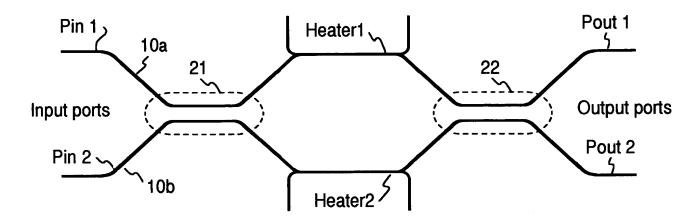


FIG. 2 (Prior Art)



TITLE: A PLANAR LIGHTWAVE CIRCUIT ACTIVE DEVICE METALLIZATION PROCESS INVENTOR(S): Pamela S. Trammel, Jonathan G. Bornstein, and David H. Menche

USSN: 09/940,567 Attorney Docket #: LWM-A110

3/7

Cross Section A-A'

<u>300</u>

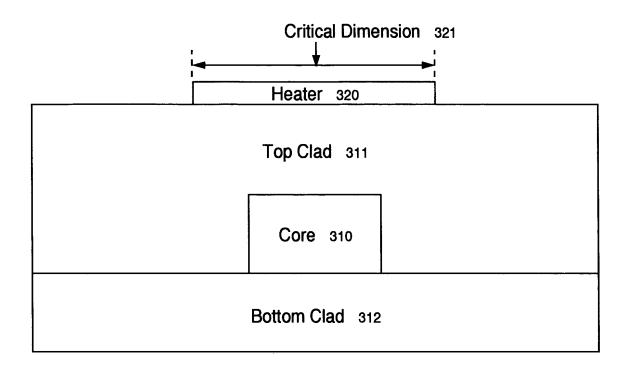


FIG. 3



4/7

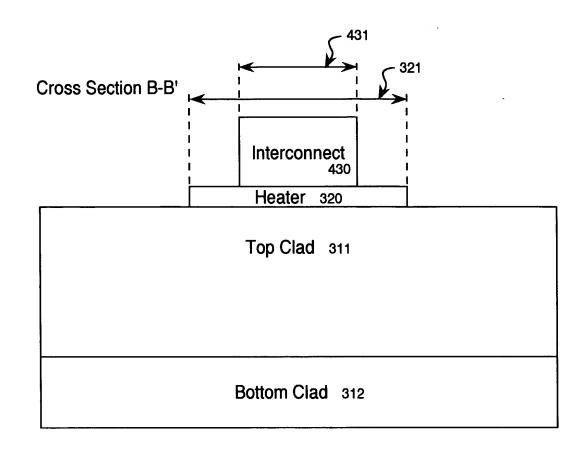


FIG. 4



5/7

Top Down

<u>300</u>

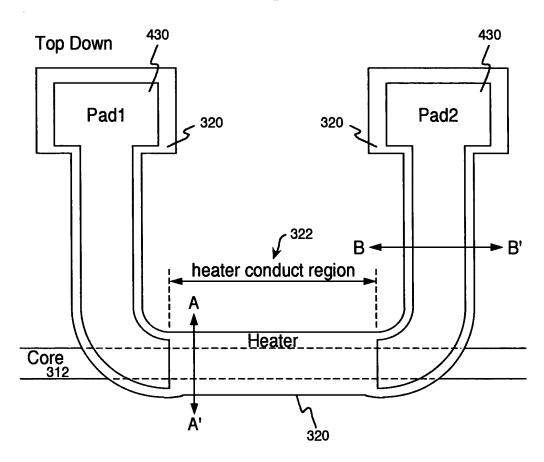


FIG. 5



6/7

Aluminum 602			
Tungsten 601			
Top Clad 311			

FIG. 6

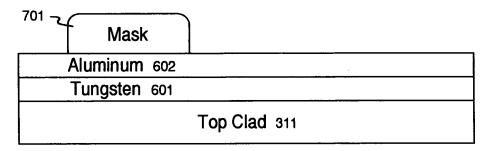


FIG. 7

Aluminum 430			
Tungsten 601			
Top Clad 311			

FIG. 8

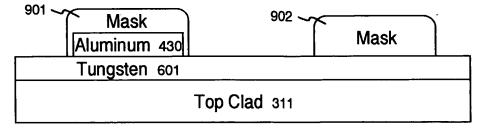


FIG. 9



7/7

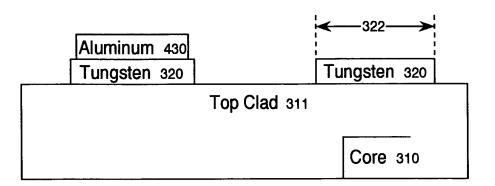


FIG. 10